

# SAQUA Single Wafer System

## System Overview

The Saqua series of 300 mm single-wafer cleaning system utilizes single wafer, precisely controlled spin-spray wet cleaning technology to remove a variety of post metal etch particles and byproducts. The Saqua can be configured with up to eight independent process chambers designed for cleaning feature sizes as small as 14 nm.

**Substrate Size:** 300 mm

**Applicable Material:** Silicon

**Technology Markets:** Digital IC, Power IC, Advanced Packaging

## Processes

- Copper Interconnect Cleaning:
  - Post etch clean on via
  - Post etch clean on trench
  - Post etch clean on liner removal
  - Post etch clean on metal hard mask
  - Post etch clean on inter metal etch
  - Backside clean



SAQUA Single Wafer System

## Production Advantages

- Multitasking parallel processing system; up to eight independently controlled process chambers
- Advanced megasonic cleaning technology
- Liquid chemical ratio real-time control technology
- Particle removal efficiency >99%
- High chemical reclaim efficiency - >99.5%
- Uniform chemical temperature and flow rate control across all process chambers
- Novel wafer backside protection technology
- Independent clean/dirty robots